



Mini-Circuits

THIN FILM SURFACE MOUNT

Bandpass Filter

ABF-11R8G+

50Ω

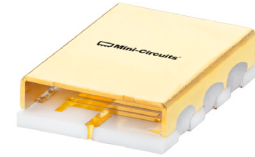
10.6 to 13 GHz

KEY FEATURES

- Low Passband Insertion Loss of 1 dB Typ.
- High Rejection of 53 dB Typ.
- Good Return Loss of 16 dB Typ.
- Small Size, 5.59 x 8.13 x 2.03 mm

APPLICATIONS

- X-Band Radar
- Test and Measurements

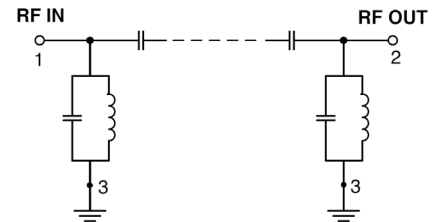


Generic photo used for illustration purposes only

PRODUCT OVERVIEW

Mini-Circuits' Surface Mount Thin-Film filters offer low insertion loss and high rejection realized via Thin-Film on Alumina substrate, using a sputtering process that can guarantee an enhanced Q and repeatable performance. Low pass, high pass, and bandpass surface mount thin-film designs can be realized with this technology up to 40 GHz in a small form factor helping customers achieve their SWaP objectives. Using our high quality thin-film manufacturing process we can guarantee repeatability on large batches of filters.

FUNCTIONAL DIAGRAM



ELECTRICAL SPECIFICATIONS^{1,2,3} AT +25°C

Parameter		F#	Frequency (GHz)	Min.	Typ.	Max.	Units
Pass Band	Center Frequency ⁴	—	—	—	11.8	—	GHz
	Insertion Loss	F1-F2	10.6 - 13	—	1	1.8	dB
	Return Loss	F1-F2	10.6 - 13	—	16	—	dB
Stopband, Lower	Rejection	DC-F3	DC - 7	45	53	—	dB
		F3-F4	7 - 8.4	20	35	—	
Stopband ,Upper	Rejection	F5-F6	15.5 - 16.5	20	48	—	dB
		F6-F7	16.5 - 19.5	33	41	—	
		F7-F8	19.5 - 25	22	30	—	
		F8-F9	25 - 27	—	20	—	

1. Tested on Evaluation Board P/N TB-ABF-11R8G+ with feedline losses removed by normalization of S12 and S21 traces to measurement of TB thru-line.

2. This filter is bi-directional RF1 and RF2 ports may be interchanged, see S-Parameters for actual performance.

3. This component is not intended for use as a DC-blocking circuit element. In applications where DC voltage and/or current is present at either the input or output ports, external DC blocking capacitors are required.

4. Typical variation ±3%.

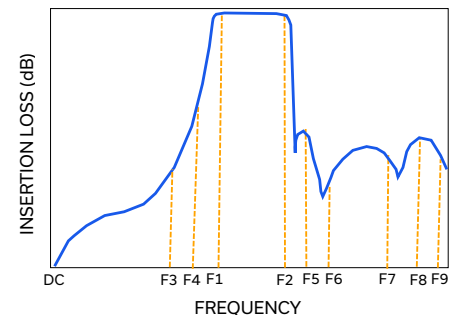
ABSOLUTE MAXIMUM RATINGS⁵

Parameter	Ratings
Operating Temperature	-55°C to +125°C
Storage Temperature	-55°C to +125°C
Input Power ⁶	8.75 W Max. at 25°C

5. Permanent damage may occur if any of these limits are exceeded.

6. Power rating applies only to signals within the passband. Derated power at +125°C is 3.3 W

TYPICAL FREQUENCY RESPONSE AT +25°C



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REV. OR
ECO-024893
ABF-11R8G+
EDU4857
URJ
250318

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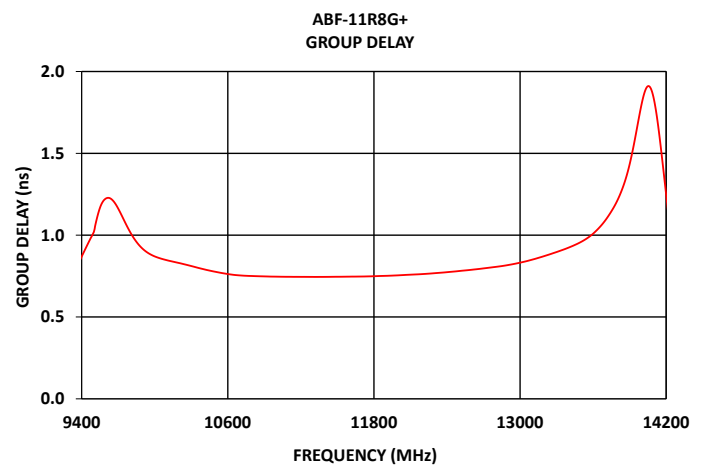
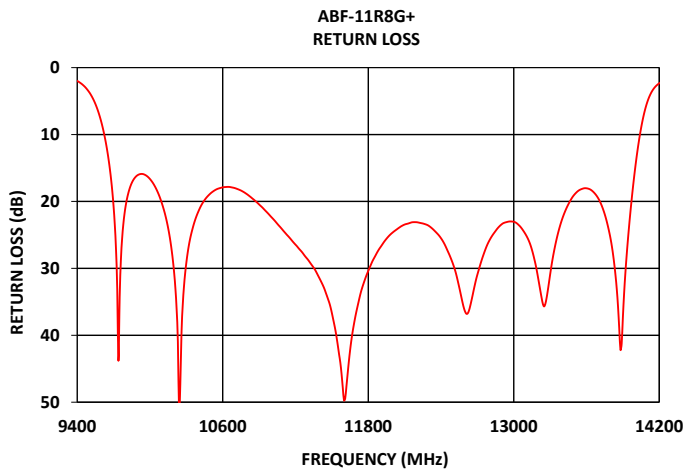
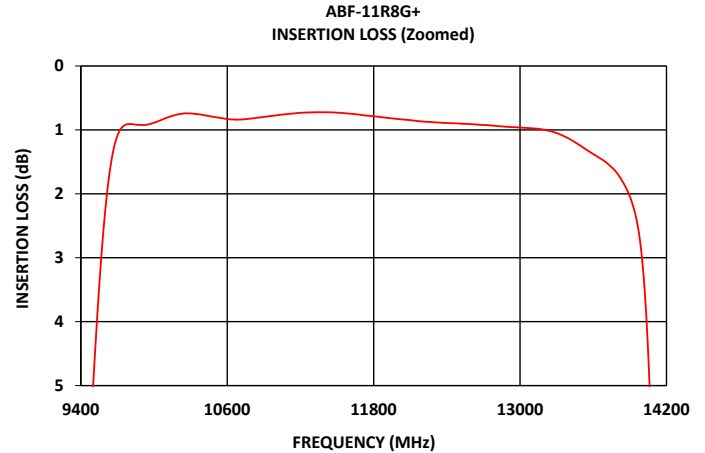
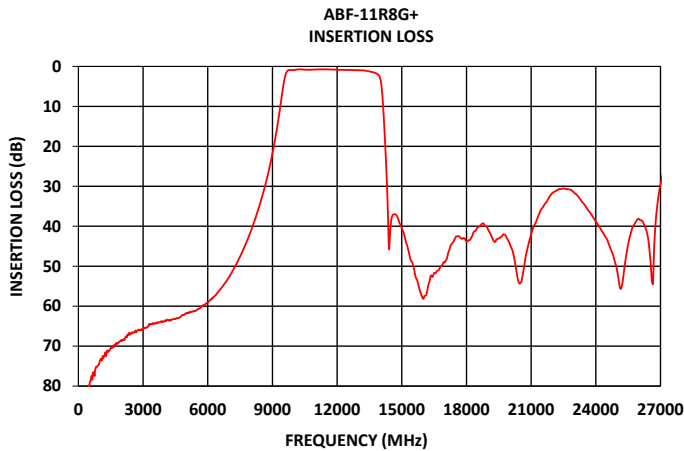
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10.6 to 13 GHz

TYPICAL PERFORMANCE GRAPHS AT +25°C





Bandpass Filter

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PAD DESCRIPTION

Function	Pad Number	Description
RF1 ²	1	Connects to RF Input Port
RF2 ²	2	Connects to RF Output Port
GROUND	3	Connects to Ground on PCB, (See drawing PL-764)
NC	—	No connection, not used internally. See drawing PL-764 for connection to PCB

Figure 1: Pin 1 location and dimensions. The diagram shows a square package with a grid of pins. A central square area is highlighted in green, representing the 'PACKAGE OUTLINE'. The pins are represented by pink circles. A specific pin is labeled 'PIN 1' with an 'INDEX' line pointing to it. Dimensions are provided for the overall package size (0.220 inches vertically, 0.294 inches horizontally), the central package outline (0.290 inches horizontally), and the pin pitch (0.013 inches space width, 0.015 inches trace width). The pins are labeled '0.010 TYP PLUGGED PTH'.

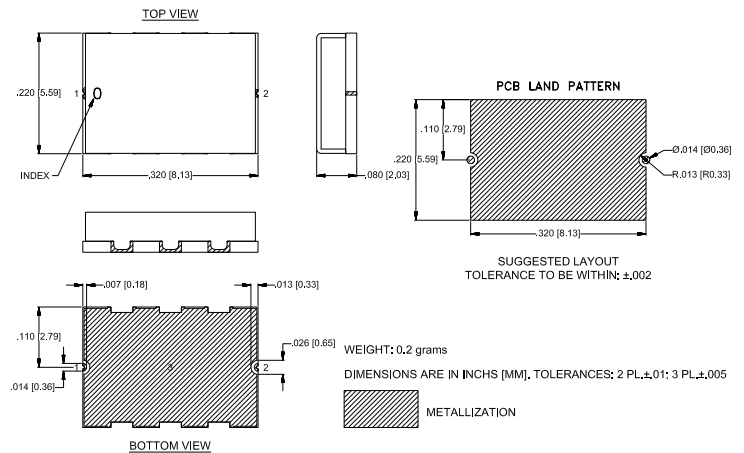
1. COPLANAR WAVEGUIDE PARAMETERS ARE SHOWN FOR ROGERS (RO4350B Lo Pro) WITH DIELECTRIC THICKNESS .0073x.0007. COPPER: 1/2 Oz. EACH SIDE. FOR OTHER MATERIALS TRACE WIDTH AND GAP MAY NEED TO BE MODIFIED.

2. BOTTOM SIDE OF THE PCB IS CONTINUOUS GROUND PLANE.

 DENOTES PCB COPPER PATTERN WITH SMOBC (SOLDER MASK OVER BARE COPPER)

 DENOTES PCB COPPER PATTERN FREE OF SOLDERMASK

CASE STYLE DRAWING



*Marking may contain other features or characters for internal lot control.



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THIN FILM SURFACE MOUNT

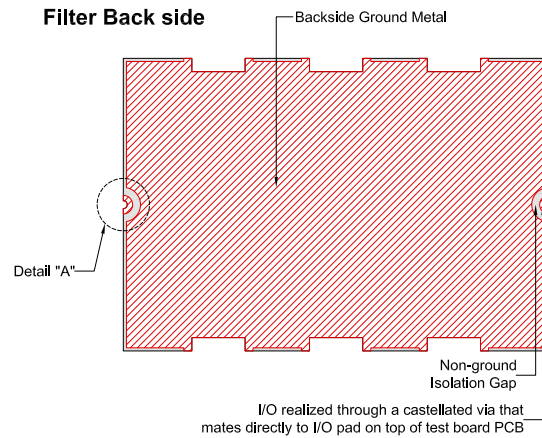
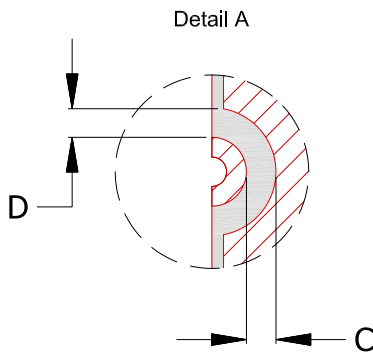
Bandpass Filter

ABF-11R8G+

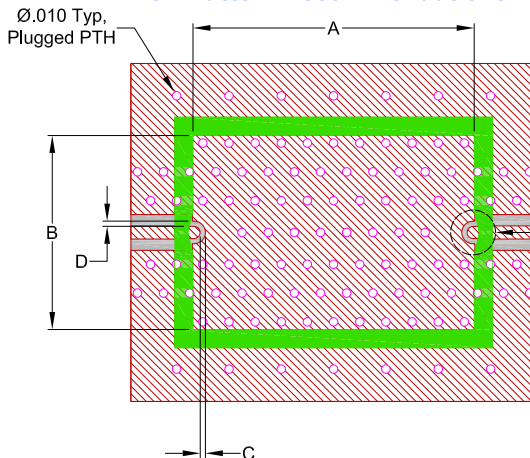
50Ω

10.6 to 13 GHz

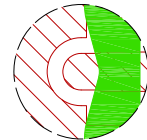
RECOMMENDED PCB LAYOUT PATTERN FOR FILTER

Filter RF I/O Detail
(Filter Back Side)

PCB Pattern Recommendations



DETAIL "B"

SEE
DETAIL "B"

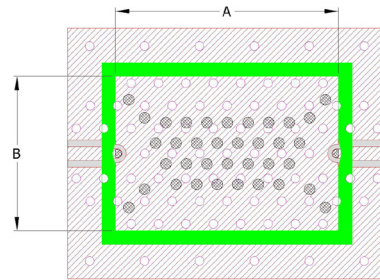
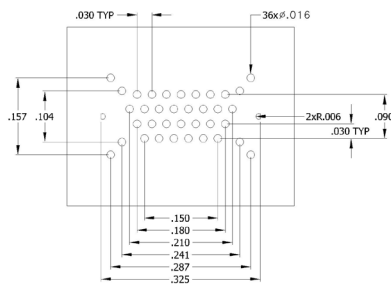
- 1) Customer PCB's ground pattern length (dimension A) can be similar to filter length.
- 2) Customer PCB's ground pattern width (dimension B) can be similar to filter width.
- 3) Dimensions C and D on Filter RF I/O detail and Customer PCB pattern can be closely match. The dimensions of C and D on the Customer PCB pattern can be slightly larger to account for component alignment tolerance (ground metal can be pulled back from RF I/O trace).
- 4) Recommend to use Solder mask at Customer PCB at outer area of filter pattern/ footprint with a clearance of about 1.25mil at each side. (Tighter registration tolerance required for solder mask)
- 5) Recommended to use Solder mask at I/O of Customer PCB as per above diagram (refer detail B).

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- 1) Avoid using soldering iron directly to the ceramic filter. This would lead to development of crack in the component due to thermal shock.
- 2) Vacuum pick-up tool or plastic tweezers are recommended for handling the components. Extra care should be taken not to scratch the filter or metal area.
- 3) Use 2-3 mil thickness stencil plate and screen print the solder. Refer below picture for recommended stencil pattern to get the best solder attachment.

Solder location after screen print



- 4) Plugged ground vias in the PWB will improve attachment consistency.
- 5) Recommended to have a similar or closer test board material and thickness (refer Mini-Circuits evaluation board for details) to minimize the CTE over the temperature range.



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ADDITIONAL DETAILED INFORMATION IS AVAILABLE ON OUR DASHBOARD.

[CLICK HERE](#)

Performance Data and Graphs	Data
	Graphs
	S-Parameter (S2P Files) Data Set (.zip file) De-embedded to device pads
Case Style	UC2731 Lead Finish: Gold over Nickel Plate.
RoHS Status	Compliant
Tape and Reel	TR-F003
Suggested Layout for PCB Design	PL-764
Evaluation Board	TB-ABF-11R8G+
	Gerber File
Environmental Rating	ENV120

NOTES

- A. Performance and quality attributes and conditions not expressly stated in this specification document are intended to be excluded and do not form a part of this specification document.
- B. Electrical specifications and performance data contained in this specification document are based on Mini-Circuits' applicable established test performance criteria and measurement instructions.
- C. The parts covered by this specification document are subject to Mini-Circuits' standard limited warranty and terms and conditions (collectively, "Standard Terms"); Purchasers of this part are entitled to the rights and benefits contained therein. For a full statement of the standard terms and the exclusive rights and remedies thereunder, please visit Mini-Circuits' website at www.minicircuits.com/terms/viewterm.html



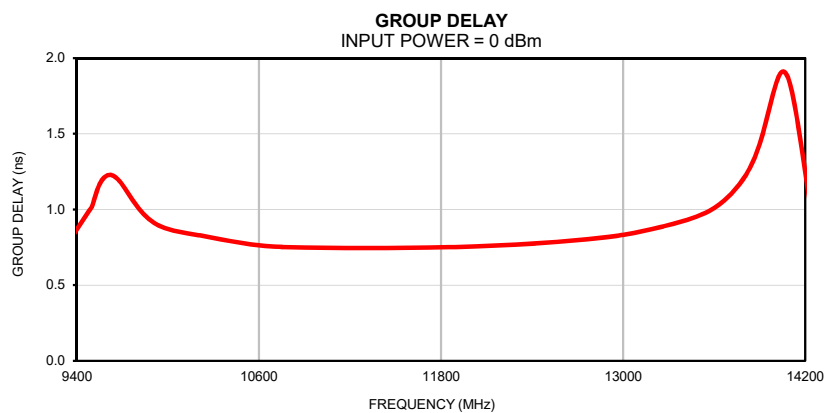
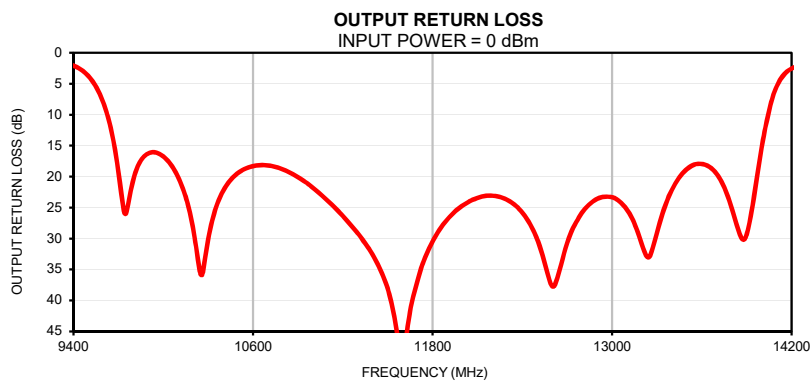
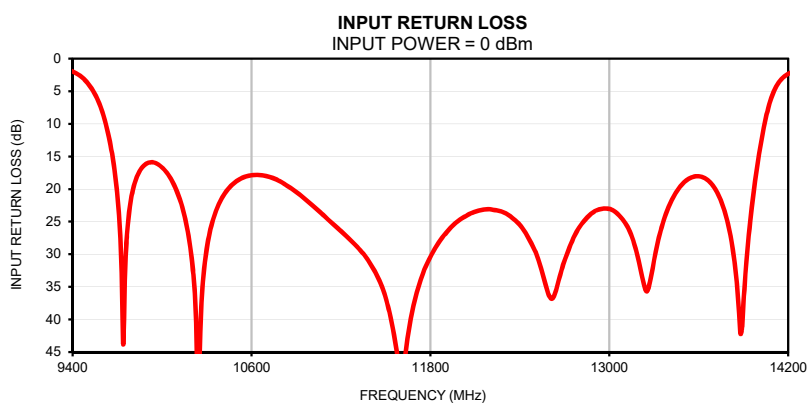
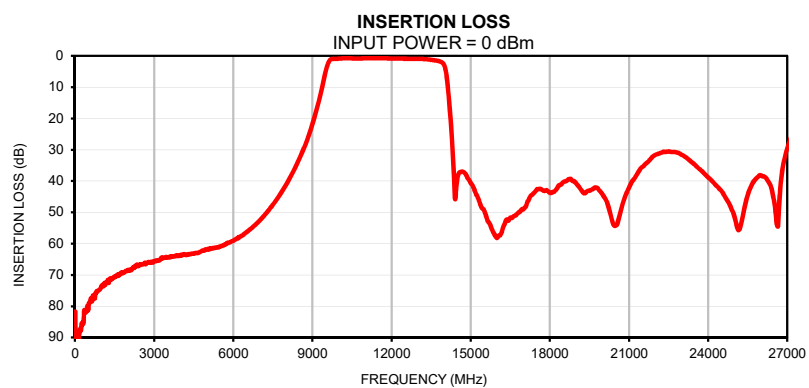
Thin-Film Bandpass Filter

ABF-11R8G+

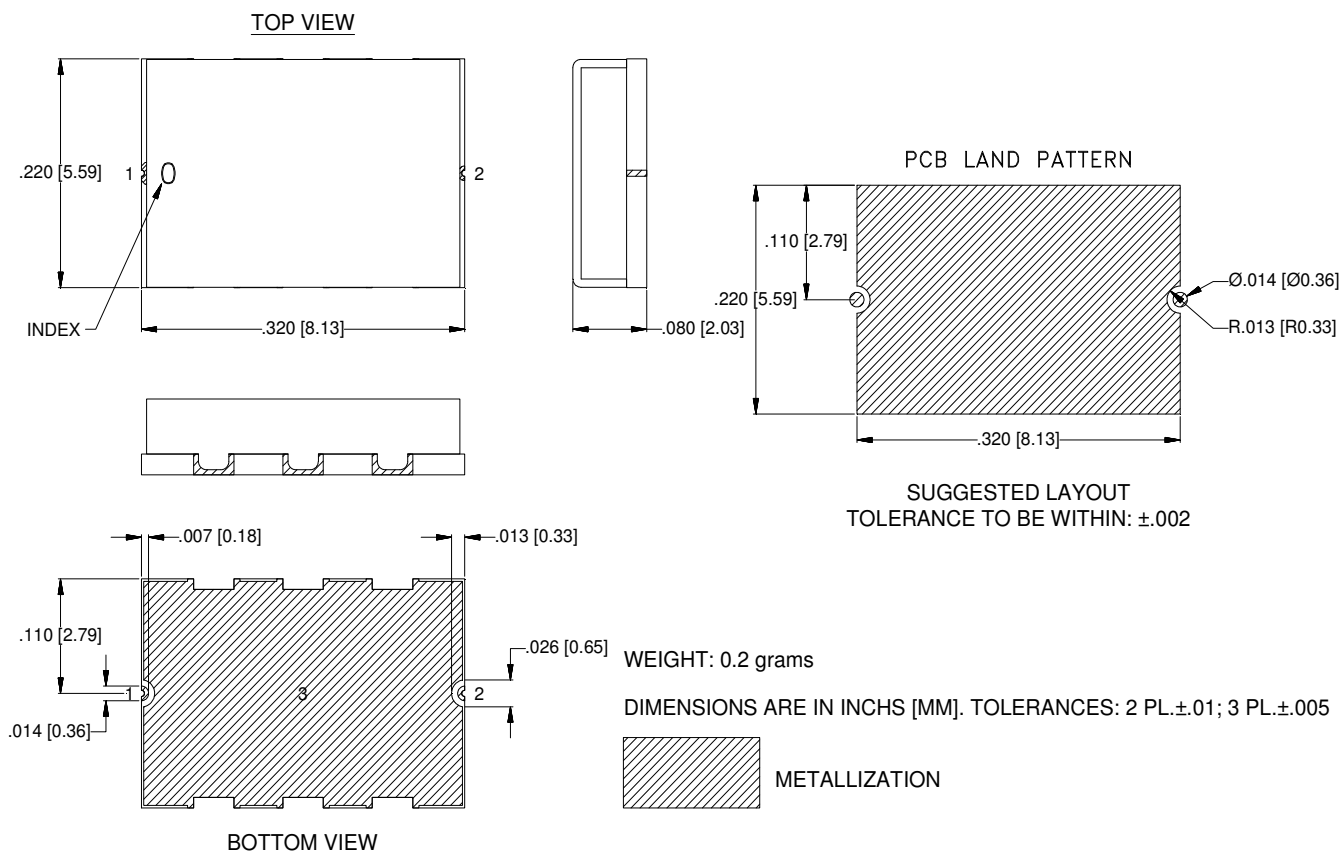
Typical Performance Data

FREQ.	Insertion Loss	Input Return Loss	Output Return Loss	FREQ.	Group Delay
(MHz)	(dB)	(dB)	(dB)	(MHz)	(ns)
10	81.69	0.02	0.04	10600	0.76
20	87.45	0.04	0.04	10650	0.76
50	98.49	0.06	0.06	10660	0.76
100	92.25	0.08	0.09	10670	0.76
300	85.74	0.16	0.17	10680	0.76
500	81.24	0.21	0.22	10690	0.75
800	75.71	0.24	0.26	10700	0.75
900	74.91	0.24	0.27	10710	0.75
1000	73.54	0.24	0.27	10720	0.75
2000	68.42	0.20	0.23	10730	0.75
4000	63.77	0.32	0.34	10740	0.75
6000	59.06	0.53	0.60	10800	0.75
7000	52.62	0.66	0.67	10820	0.75
8400	34.78	0.75	0.78	10840	0.75
8650	30.06	0.74	0.81	10860	0.75
9050	20.46	0.85	0.96	10880	0.75
10000	0.89	16.65	16.71	10900	0.75
10600	0.83	17.89	18.29	10920	0.75
11000	0.77	22.32	21.78	10940	0.75
11200	0.73	26.46	26.31	10960	0.75
11400	0.72	31.56	32.61	10980	0.75
11500	0.73	36.67	38.04	11000	0.75
11800	0.79	30.39	30.55	11050	0.75
11900	0.81	26.85	26.91	11100	0.75
12000	0.83	24.66	24.68	11150	0.75
12200	0.87	23.10	23.08	11180	0.75
12400	0.89	25.50	25.78	11200	0.75
12600	0.91	36.51	37.69	11250	0.75
12800	0.94	25.80	25.77	11280	0.75
13000	0.96	23.03	23.31	11300	0.75
14000	3.02	15.22	15.40	11350	0.74
15000	40.55	1.26	1.28	11400	0.75
15500	49.23	1.29	1.28	11450	0.75
16000	58.15	1.29	1.32	11500	0.75
16500	51.70	1.26	1.33	11550	0.75
17000	49.02	1.21	1.31	11600	0.75
17500	42.68	1.20	1.32	11650	0.75
18000	43.77	1.20	1.32	11700	0.75
18500	40.40	1.27	1.35	11750	0.75
19000	40.78	1.33	1.37	11800	0.75
19200	42.96	1.34	1.38	11850	0.75
19400	43.33	1.38	1.40	11900	0.75
19500	43.06	1.40	1.41	12000	0.75
19600	42.63	1.42	1.42	12050	0.76
19700	42.06	1.44	1.44	12100	0.76
19800	42.19	1.45	1.45	12200	0.76
19850	42.71	1.45	1.45	12250	0.76
20000	44.28	1.46	1.46	12300	0.77
20100	45.61	1.46	1.47	12350	0.77
20200	47.60	1.47	1.48	12400	0.77
20400	53.66	1.50	1.51	12450	0.78
20600	52.40	1.53	1.52	12500	0.78
20800	46.24	1.53	1.55	12550	0.78
21000	42.07	1.52	1.56	12600	0.79
22000	31.65	1.53	1.68	12650	0.79
23000	31.64	1.45	1.65	12700	0.80
24000	38.83	1.47	1.62	12750	0.80
25000	51.48	1.77	1.79	12800	0.81
26000	38.16	2.18	2.08	12900	0.82
27000	29.56	2.48	2.73	13000	0.83

Typical Performance Curves



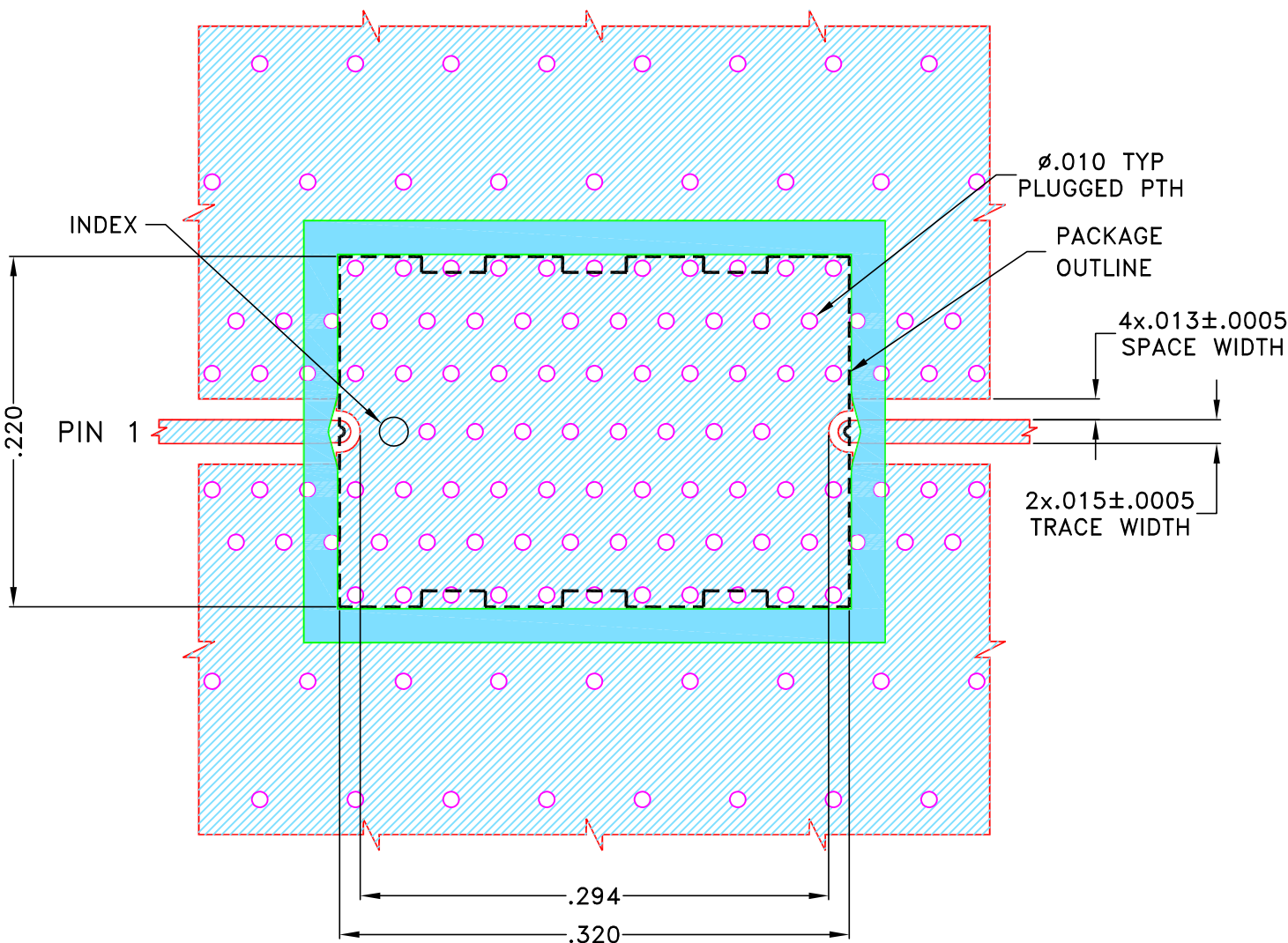
UC2731



1. Case material: Gold over Nickel over Annealed Stainless Steel.
2. Base: Ceramic
3. Termination finish: **as shown below or indicated on Data Sheet.**
For RoHS Case Styles: Gold over Nickel plate. All models, (+) suffix.

THIRD ANGLE PROJECTION		REVISIONS				
	REV	ECN No.	DESCRIPTION	DATE	DR	AUTH
	OR	NPO-003903	NEW RELEASE	OCT 23	LK	VC

SUGGESTED MOUNTING CONFIGURATION
FOR UC2731 CASE STYLE



NOTES:

1. COPLANAR WAVEGUIDE PARAMETERS ARE SHOWN FOR ROGERS (R04350B Lo Pro) WITH DIELECTRIC THICKNESS .0073±.0007. COPPER: 1/2 Oz. EACH SIDE.
FOR OTHER MATERIALS TRACE WIDTH AND GAP MAY NEED TO BE MODIFIED.

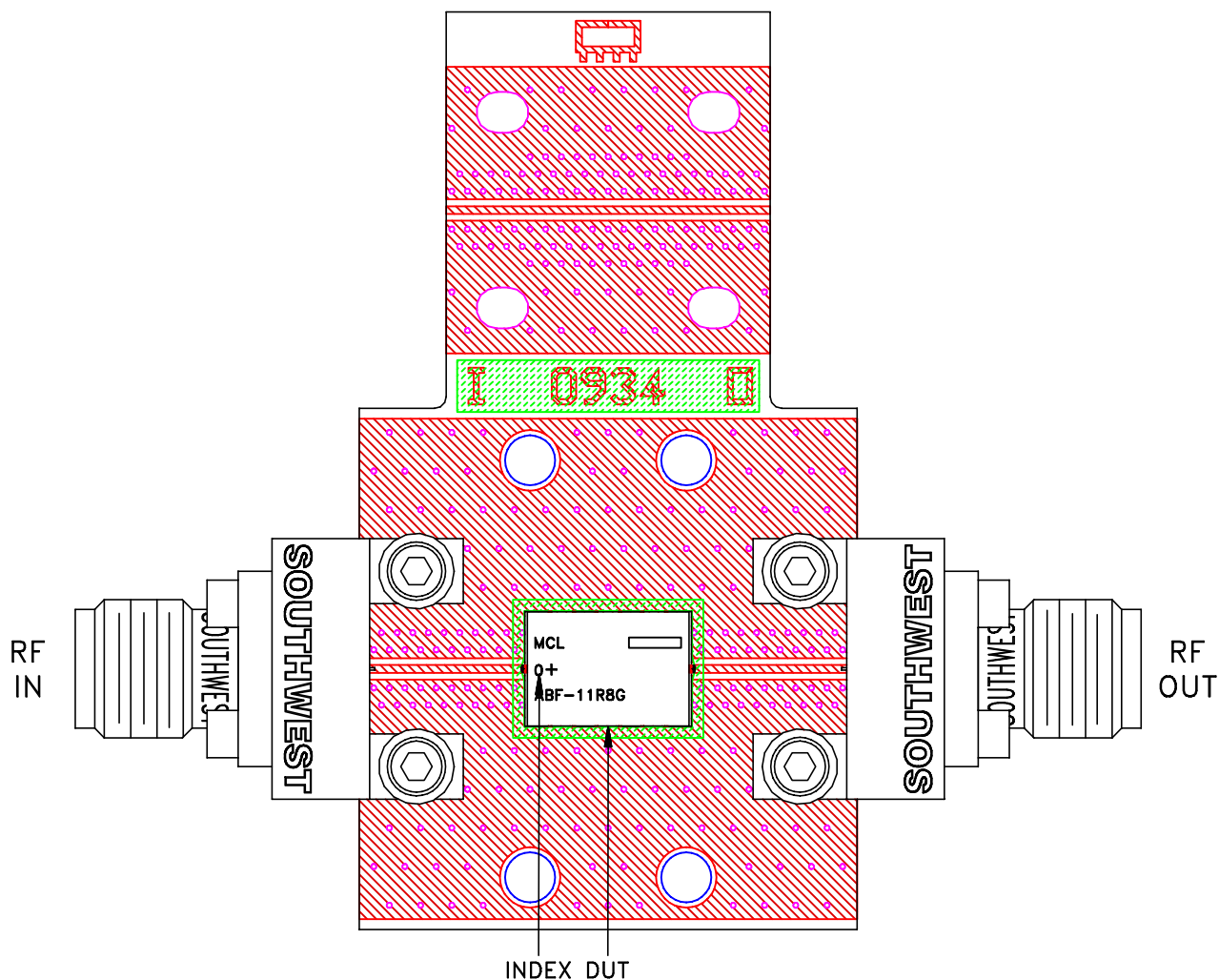
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 DENOTES PCB COPPER PATTERN WITH SMOBC (SOLDER MASK OVER BARE COPPER)
 DENOTES PCB COPPER PATTERN FREE OF SOLDERMASK

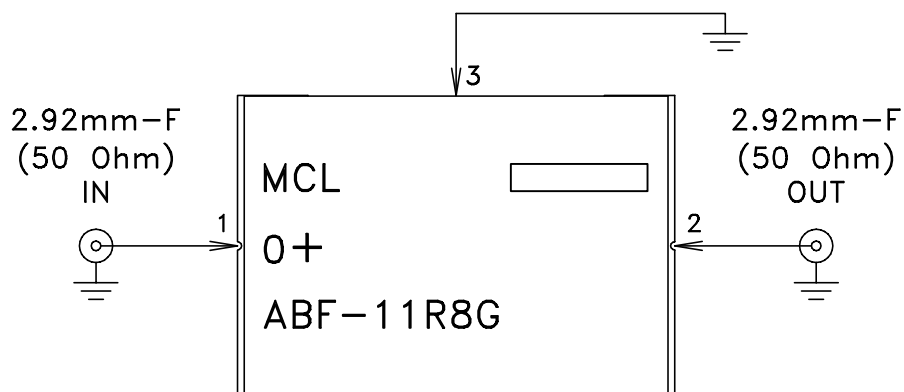
UNLESS OTHERWISE SPECIFIED		INITIALS		DATE		Mini-Circuits® 13 Neptune Avenue Brooklyn NY 11235							
DIMENSIONS ARE IN INCHES TOLERANCES ON: 2 PL DECIMALS ± 3 PL DECIMALS ± .005 ANGLES ± FRACTIONS ±		DRAWN	LK	09 OCT 23		PL DWG, UC2731 C.S, 50 OHM, ALF							
		CHECKED	MD	09 OCT 23									
		APPROVED	RR	13 OCT 23									
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ASHEETA1.DWG REV:A DATE:01/12/95						FILE: 98-PL-764		SCALE: 9.1:1		SHEET: 1 OF 1			

Evaluation Board and Circuit

TB-ABF-11R8G+



Schematic diagram



Notes:

1. PCB Material: ROGERS (R04350B Lo Pro) OR Equivalent, Dielectric Constant= $3.48 \pm .05$
Dielectric Thickness: $.0073 \pm .0007$ inch
2. 50 Ohm 2.92mm Female Connectors.

 **Mini-Circuits®**



All Mini-Circuits products are manufactured under exacting quality assurance and control standards, and are capable of meeting published specifications after being subjected to any or all of the following physical and environmental test.

Specification	Test/Inspection Condition	Reference/Spec
Operating Temperature	-55° to 125° C Ambient Environment	Individual Model Data Sheet
Storage Temperature	-55° to 125° C Ambient Environment	Individual Model Data Sheet
Solderability	10X Magnification	J-STD-002, Para 4.2.5, Test S, 95% Coverage
Thermal Shock	-55° to 125°C, 100 cycles	MIL-STD-202, Method 107, Condition A-3, Except +125°C